



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-11-07
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGP3NC120HD	TDDZ*IVJ2GW2	A	SHENZHEN B/E	2016-11-07
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TDDZ*IVJ2GW2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	8.078	mg	supplier	die	Silicon (Si)	7440-21-3		7.787	mg	963976	4098
				supplier	metallization	Aluminium (Al)	7429-90-5		0.140	mg	17331	74
				supplier	Passivation	Silicon Nitride	12033-89-5		0.031	mg	3838	16
				supplier	Passivation	Silicon Oxide	7631-86-9		0.043	mg	5323	23
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	123	1
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	619	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	248	1
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.053	mg	6561	28
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.016	mg	1981	8
				supplier	back side metallization	Copper (Cu)	7440-50-8		1251.376	mg	998278	658619
Leadframe	Copper & its alloys	1253.535	mg	supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
				supplier	metallization	Nickel (Ni)	7440-02-0		0.490	mg	390	258
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	32	21
				supplier	metallization	Lead (Pb)	7439-92-1	7a-Lead in high me	1.333	mg	954871	702
Soft solder	Solder	1.396	mg	supplier	solder	Silver (Ag)	7440-22-4		0.035	mg	25072	17
				supplier	solder	Tin (Sn)	7440-31-5		0.028	mg	20057	15
				supplier	solder	Aluminium (Al)	7429-90-5		0.581	mg	998282	306
Bonding wires	Other inorganic materials	0.582	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	1718	1
				supplier	wire	Aluminium (Al)	7429-90-5		0.581	mg	998282	306
Encapsulation	Other Organic Materials	630.047	mg	supplier	mold compound	Silica, vitreous	60676-86-0		548.141	mg	870000	288495
				supplier	mold compound	Epoxy resin	25068-38-6		63.005	mg	100000	33161
				supplier	mold compound	Phenol resin	29690-82-2		15.751	mg	25000	8290
				supplier	mold compound	Carbon Black	1333-86-4		3.150	mg	5000	1658
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348